

3.3 V Quad LVCMOS Differential Line Receiver Translator

NB3N4666C

Description

The NB3N4666C is a quad-channel LVDS line receiver/translator offering data rates up to 400 Mbps (200 MHz) and low power consumption. The NB3N4666C receiver incorporates input fail-safe protection circuit that provides a known output voltage under input open-circuit and terminated (100 Ω) conditions. The four independent inputs accept differential signals such as: M-LVDS, LVDS, LVPECL and HCSL and translates them to a single-ended, 3.3 V LVCMOS.

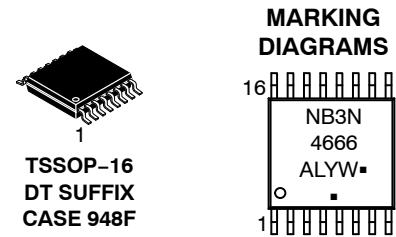
The NB3N4666C also offers active high and active low enable/disable inputs (EN and $\overline{\text{EN}}$) that allow users to control outputs of all four receivers. These inputs enable or disable the receivers and switch the outputs to an active or high impedance state respectively (see Table 2). The high impedance mode feature helps to reduce the quiescent power consumption to less than 10 mW typical, when the outputs of one or more NB3N4666C devices are multiplexed together.

Features

- Accepts M-LVDS, LVDS, LVPECL and HCSL Differential Input Signal Levels
- Maximum Data Rate of 400 Mbps
- Maximum Clock Frequency of 200 MHz
- 25 ps Typical Channel-to-Channel Skew
- 3.3 ns Maximum Propagation Delay
- 3.3 V $\pm 10\%$ Power Supply
- High Impedance Outputs When Disabled
 - ♦ Low Quiescent Power < 10 mW Typical
- Supports Open and Terminated Input Fail-safe
- -40°C to $+85^{\circ}\text{C}$ Ambient Operating Temperature
- 16-Pin TSSOP, 5.0 mm x 4.4 mm x 1.2 mm
- These are Pb-Free Devices

Applications

- Point-to-point Data Transmission
- Backplane Receivers
- Clock Distribution Networks
- Multidrop Buses



A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

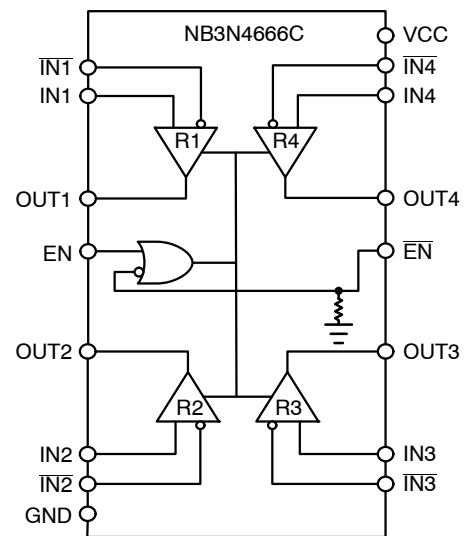


Figure 1. Functional Block Diagram

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

NB3N4666C

Table 1. PIN DESCRIPTION

| Pin TSSOP | Name | I/O | Description |
|-----------|-------------------------|-----------------------|--|
| 1 | $\overline{\text{IN}}1$ | Input | Receiver Channel 1 Inverted Input. |
| 2 | IN1 | Input | Receiver Channel 1 Non-inverted Input. |
| 3 | OUT1 | LVC MOS Output | Receiver Channel 1 Output. |
| 4 | EN | Input Enable | Active High Enable. See Table 2 for output enable function. |
| 5 | OUT2 | LVC MOS Output | Receiver Channel 2 Output. |
| 6 | IN2 | Input | Receiver Channel 2 Non-inverted Input. |
| 7 | $\overline{\text{IN}}2$ | Input | Receiver Channel 2 Inverted Input. |
| 8 | GND | Power | Power Supply Ground (Note 1) |
| 9 | $\overline{\text{IN}}3$ | Input | Receiver Channel 3 Inverted Input. |
| 10 | IN3 | Input | Receiver Channel 3 Non-inverted Input. |
| 11 | OUT3 | LVC MOS Output | Receiver Channel 3 Output. |
| 12 | $\overline{\text{EN}}$ | Inverted Input Enable | Active Low Enable. Defaults Low when left open; internal pull-down resistor. See Table 2 for output enable function. |
| 13 | OUT4 | LVC MOS Output | Receiver Channel 4 Output. |
| 14 | IN4 | Input | Receiver Channel 4 Non-inverted Input. |
| 15 | $\overline{\text{IN}}4$ | Input | Receiver Channel 4 Inverted Input. |
| 16 | V _{CC} | Power | 3.3 V \pm 10% Positive Supply Voltage (Note 1) |

1. All V_{CC} and GND pins must be externally connected to a power supply for proper operation. Bypass each supply pin with 0.01 μ F to GND.

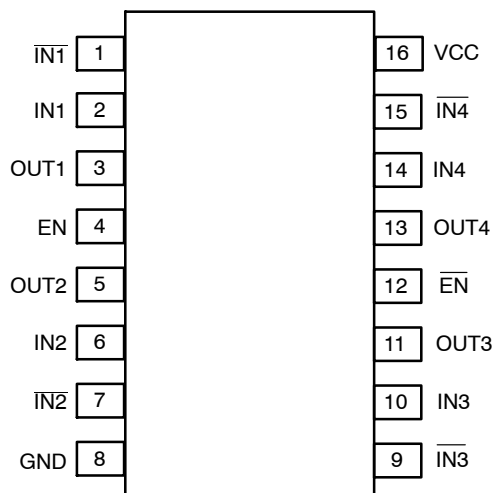


Figure 2. TSSOP-16 Pinout (Top View)

Table 2. OUTPUT ENABLE FUNCTION

| ENABLES | | INPUTS | OUTPUT |
|---|----|--------------------------------------|--------|
| EN | EN | IN, $\overline{\text{IN}}$ | OUT |
| L | H | X | Z |
| All other combinations of ENABLE inputs | | $V_{\text{ID}} \geq 100 \text{ mV}$ | H |
| | | $V_{\text{ID}} \leq -100 \text{ mV}$ | L |
| | | Full Fail-safe OPEN or Terminated | H |

Fail-Safe Feature

The multi-level receiver's internal fail-safe circuitry is designed to provide fail-safe protection for floating/open or terminated receiver inputs, and will output a stable High-level voltage state.

Open Input Pins. The NB3N4666C is a quad receiver device, and if an application requires only 1, 2 or 3 receivers, the unused channel(s) inputs should be left OPEN. The internal input circuitry will ensure a HIGH stable output state for open inputs.

Terminated Input. If the driver to the input is disconnected, in a TRI-STATE or power-off condition, the output will again be in a HIGH state, even with a 100- Ω termination resistor across the input pins.

Do not connect unused receiver inputs to ground or any other voltages.

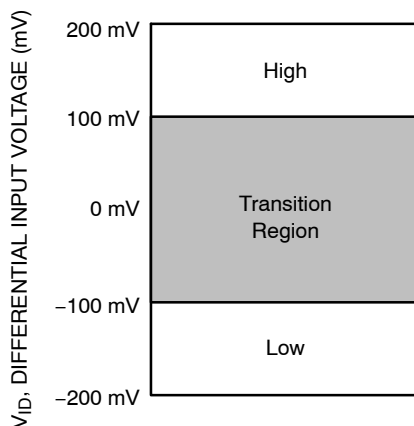


Figure 3. Receiver Differential Input Voltage Showing Transition Region

Table 3. ATTRIBUTES (Note 2)

| Characteristics | | Value |
|--|------------------------|----------------------|
| ESD Protection | Human Body Model | 6 kV |
| | Charged Device Model | 500 V |
| C_{IN} – Input Capacitance | | 4 pF typical |
| R_{IN} – Input Impedance | | > 10 k Ω |
| R_{PD} – Inverted Input Enable Pull-down Resistor | | 800 k Ω |
| Moisture Sensitivity | | Level 1 |
| Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in |
| Transistor Count | | 621 |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test | | |

2. For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
|---------------|--|-------------|-------------|------------------------|------|
| V_{CC} | Supply Voltage Range | GND = 0 V | | 4.6 | V |
| V_{IN} | Input Voltage Range | GND = 0 V | | -0.5 to $V_{CC} + 0.5$ | V |
| T_A | Operating Temperature Range | | | -40 to +85 | °C |
| T_{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) | 0 lfpm | TSSOP-16 | 138 | °C/W |
| | | 500 lfpm | TSSOP-16 | 108 | |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | 2S2P | TSSOP-16 | 33-36 | °C/W |
| T_{sol} | Wave Solder (Pb-Free) | | | 265 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 5. DC CHARACTERISTICS ($V_{CC} = 3.3 \text{ V} \pm 10\%$; $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

| Symbol | Characteristic | Min | Typ | Max | Unit |
|--------|----------------|-----|-----|-----|------|
|--------|----------------|-----|-----|-----|------|

POWER SUPPLY

| | | | | | |
|-----------|---|------|------|------|----|
| V_{CC} | Power Supply Voltage | 2.97 | 3.30 | 3.63 | V |
| I_{CC} | No Load Supply, All Receivers Enabled ($EN = V_{CC}$, $\overline{EN} = \text{GND}$, inputs open) | | 10 | 15 | mA |
| I_{CCZ} | No Load Supply, All Receivers Disabled ($EN = \text{GND}$ and $\overline{EN} = V_{CC}$, inputs open) | | 3 | 5.5 | mA |
| P_D | Power Dissipation (Note 6) | | | 300 | mW |

LVCMOS OUTPUTS

| | | | | | |
|----------|---|-----|---------|------|---------------|
| V_{OH} | Output High Voltage $I_{OH} = -0.4 \text{ mA}$, $V_{ID} = +200 \text{ mV}$ $I_{OH} = -0.4 \text{ mA}$, Input Terminated (100 Ω Across Differential Inputs) $I_{OH} = -0.4 \text{ mA}$, Input Shorted | 2.7 | 3.0 | | V |
| | | 2.7 | 3.0 | | |
| | | 2.7 | 3.0 | | |
| V_{OL} | Output Low Voltage $I_{OL} = 2 \text{ mA}$, $V_{ID} = -200 \text{ mV}$ | GND | 0.1 | 0.25 | V |
| I_{OS} | Output Short Circuit Current (Note 4) Outputs enabled, $V_{OUT} = 0 \text{ V}$ | -15 | -48 | -120 | mA |
| I_{OZ} | Output Off State Current Outputs disabled, $V_{OUT} = 0 \text{ V}$ or V_{CC} | -10 | ± 1 | +10 | μA |

CONTROL INPUTS (EN , \overline{EN})

| | | | | | |
|----------|---|------|---------|----------|---------------|
| V_{IH} | Input HIGH Voltage $V_{CC} = 3.3 \text{ V}$ | 2.0 | | V_{CC} | V |
| V_{IL} | Input LOW Voltage $V_{CC} = 3.3 \text{ V}$ | GND | | 0.8 | V |
| I_I | Input Current $V_{IN} = 0 \text{ V}$ or V_{CC} , other input = V_{CC} or 0 V | -10 | ± 1 | +10 | μA |
| V_{CL} | Input Clamp Voltage $I_{CL} = -18 \text{ mA}$ | -1.5 | -0.9 | | V |

DIFFERENTIAL INPUTS (IN , \overline{IN})

| | | | | | |
|-----------|---|-----|---------|-----|---------------|
| V_{CMR} | Input Common Mode Range $V_{ID} = 200 \text{ mV}$ peak to peak; Differential Input Voltage (V_{ID}) (Notes 3 and 5) (Figures 6 and 7) | 0.1 | | 2.3 | V |
| I_{IN} | Input Current $V_{IN} = +2.8 \text{ V}$, $V_{CC} = 3.6 \text{ V}$ or 0 V $V_{IN} = 0 \text{ V}$, $V_{CC} = 3.6 \text{ V}$ or 0 V $V_{IN} = +3.63 \text{ V}$, $V_{CC} = 0 \text{ V}$ | -25 | ± 1 | +25 | μA |
| | | -30 | ± 1 | +30 | |
| | | -30 | | +30 | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Guaranteed by design and characterization. Not tested in production.

4. Output short-circuit current (I_{OS}) is specified as magnitude only; a minus sign indicates direction only. Note that only one output should be shorted at a time; do not exceed the maximum junction temperature specification (150°C).

5. The V_{CMR} range is reduced for larger V_{ID} . Example: if $V_{ID} = 400 \text{ mV}$, the V_{CMR} is 0.2 V to 2.2 V. A V_{ID} up to V_{CC} may be applied to the IN/\overline{IN} inputs with the Common-Mode voltage set to $V_{CC}/2$. Propagation delay and Differential Pulse skew decrease when V_{ID} is increased from 200 mV to 400 mV. Skew specifications apply for $200 \text{ mV} \leq V_{ID} \leq 800 \text{ mV}$ over the common-mode range.

6. Tested with 100 MHz input frequency on all channels, $EN = V_{CC}$, $\overline{EN} = \text{GND}$.

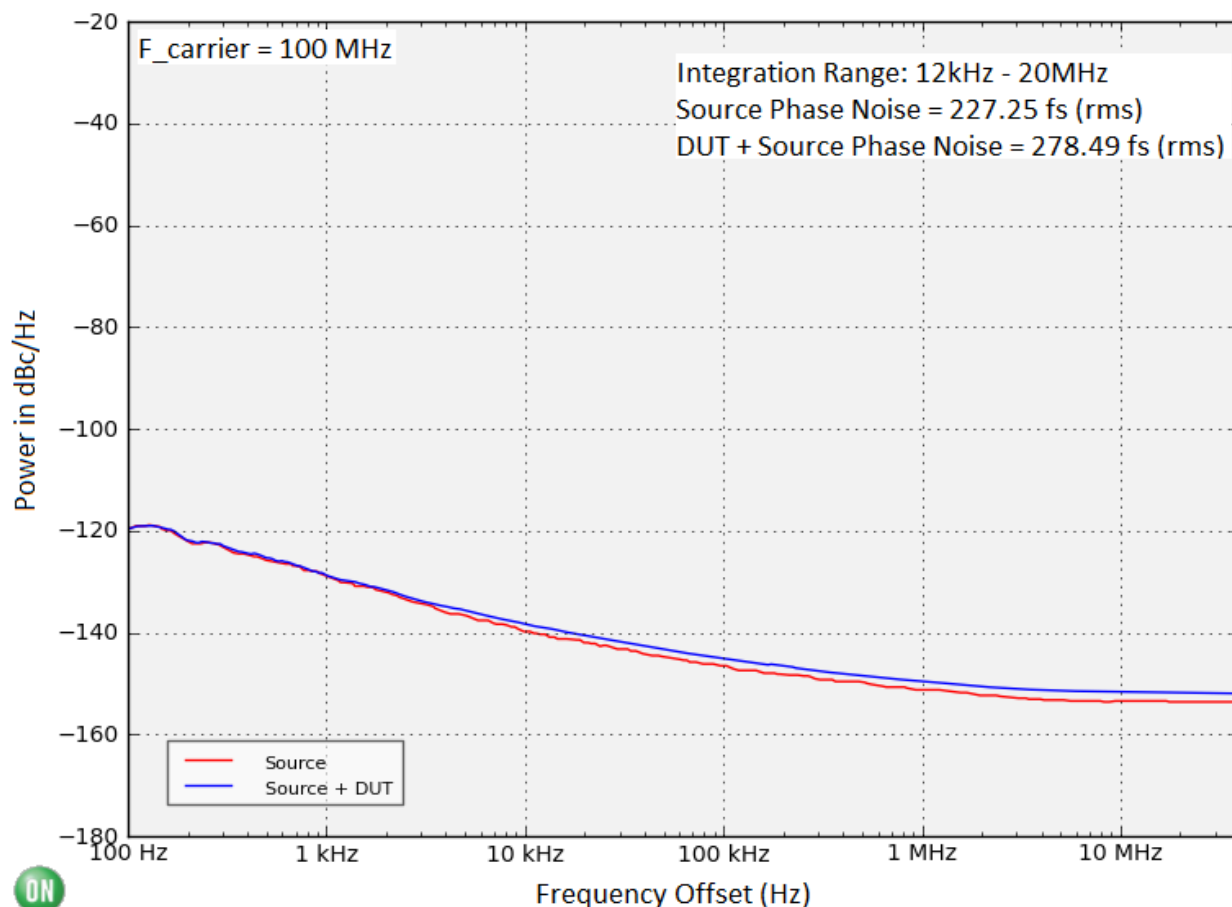
Table 6. AC CHARACTERISTICS ($V_{CC} = 3.3 \text{ V} \pm 10\%$; $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) (Note 7)

| Symbol | Characteristic | Min | Typ | Max | Unit |
|-------------------|--|-----|-----|------|------|
| f_{MAX} | Maximum Input Clock Frequency (Note 8) All Channels Switching | 200 | 250 | | MHz |
| $f_{DATAMAX}$ | Maximum Data Rate | 400 | | | Mbps |
| t_{plh}/t_{phl} | Propagation Delay (Note 9) (Figures 5 and 8) | 1.8 | | 3.3 | ns |
| $t_{SKEW(O-O)}$ | Channel-to-channel Skew (Note 10) | 0 | 25 | 250 | ps |
| $t_{SKEW(PP)}$ | Part-to-part Skew (Note 11) | | 50 | 500 | ps |
| $t_{SKEW(P)}$ | Pulse Skew $ t_{PHL} - t_{PLH} $, $V_{CM} = V_{CC}/2$ (Note 12) (Figures 5 and 8) | 0 | 50 | 300 | ps |
| t_r/t_f | Output Rise/Fall Time, 20% – 80% (Figures 5 and 8) | | 600 | 1200 | ps |
| $T_{jit}(\phi)$ | Additive RMS Phase Jitter Integration Range: 12 kHz – 20 MHz, $f_c = 100 \text{ MHz}$, 25°C , $V_{CC} = 3.3 \text{ V}$ | | 161 | | fs |
| t_{plz}/t_{phz} | Output Disable Time (Figures 9 and 10) $R_L = 2 \text{ k}\Omega$ | | 10 | 14 | ns |
| t_{pzl}/t_{pzh} | Output Enable Time (Figures 9 and 10) $R_L = 2 \text{ k}\Omega$ | | 2 | 5 | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. Generator waveform for all tests, unless otherwise specified: $f = 50 \text{ MHz}$, $C_L = 10 \text{ pF}$ (includes jig capacitance), t_r and t_f (10% to 90%) $\leq 2 \text{ ns}$ for INx/INx .
8. f_{MAX} generator input conditions: $t_r = t_f < 1 \text{ ns}$ (10% to 90%), 50% duty cycle, differential (1.05 V to 1.35 V peak to peak). Output Criteria: 40% – 60% duty cycle, V_{OL} (max 0.4 V), V_{OH} (min 2.7 V), $C_L = 10 \text{ pF}$ (stray plus probes)
9. Measured from the differential crosspoint of the input to $V_{CC}/2$ of the output.
10. $t_{SKEW(O-O)}$ is defined as skew between outputs of the same device at the same supply voltage and with equal load conditions.
11. $t_{SKEW(PP)}$ is defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
12. $t_{SKEW(P)}$ is the magnitude difference in the differential propagation delay time between the positive-going edge and the negative-going edge of the same channel.

NB3N4666C



The above phase noise data was captured using Agilent E5052A/B. The data displays the input phase noise and output phase noise used to calculate the additive phase jitter at a specified integration range. The additive RMS phase jitter contributed by the device (integrated between 12 kHz and 20 MHz) is 161 fs.

The additive RMS phase jitter performance of the fanout buffer is highly dependent on the phase noise of the input source.

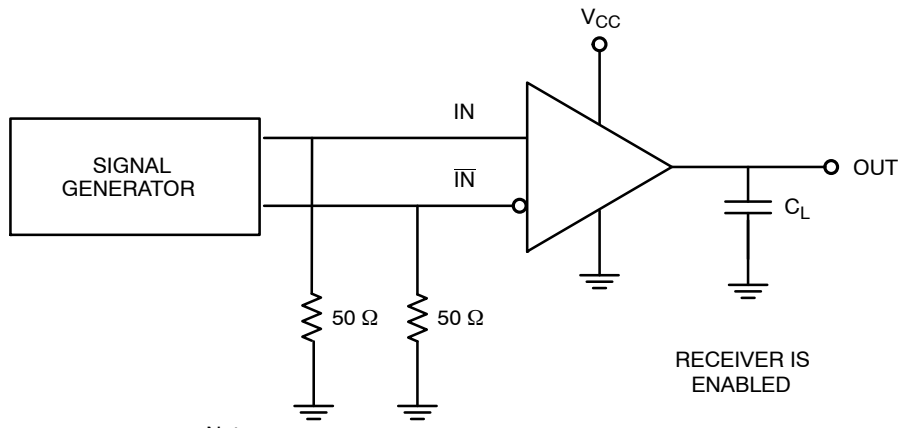
To obtain the most precise additive phase noise measurement, it is vital that the source phase noise be notably lower than that of the DUT. If the phase noise of the source is greater than the noise floor of the device under test, the source noise will dominate the additive phase jitter calculation and lead to an incorrect negative result for the additive phase noise within the integration range. The Figure above is a good example of the NB3N4666C source generator phase noise having a significantly lower floor than the DUT and results in an additive phase jitter of 161 fs.

NB3N4666C Additive RMS Phase Jitter @ 100 MHz
12 kHz to 20 MHz = 161 fs

$$\begin{aligned} \text{Additive RMS Phase Jitter} &= \sqrt{(\text{Source} + \text{DUT})^2 - (\text{Source})^2} \\ &= \sqrt{(278.49)^2 - (227.25)^2} \\ &= 161 \text{ fs} \end{aligned}$$

Figure 4. Typical Phase Noise Plot at $f_{\text{carrier}} = 100$ MHz at an Operating Voltage of 3.3 V, Room Temperature

NB3N4666C



Note:
 C_L = Load and test jig capacitance (10 pF typical)

Figure 5. AC Reference Measurement

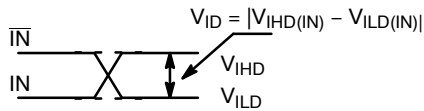


Figure 6. Differential Inputs Driven Differentially

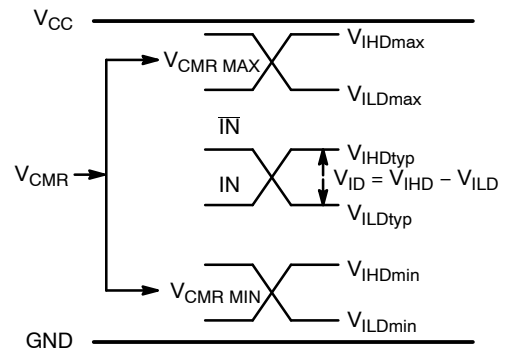


Figure 7. V_{CM} Diagram

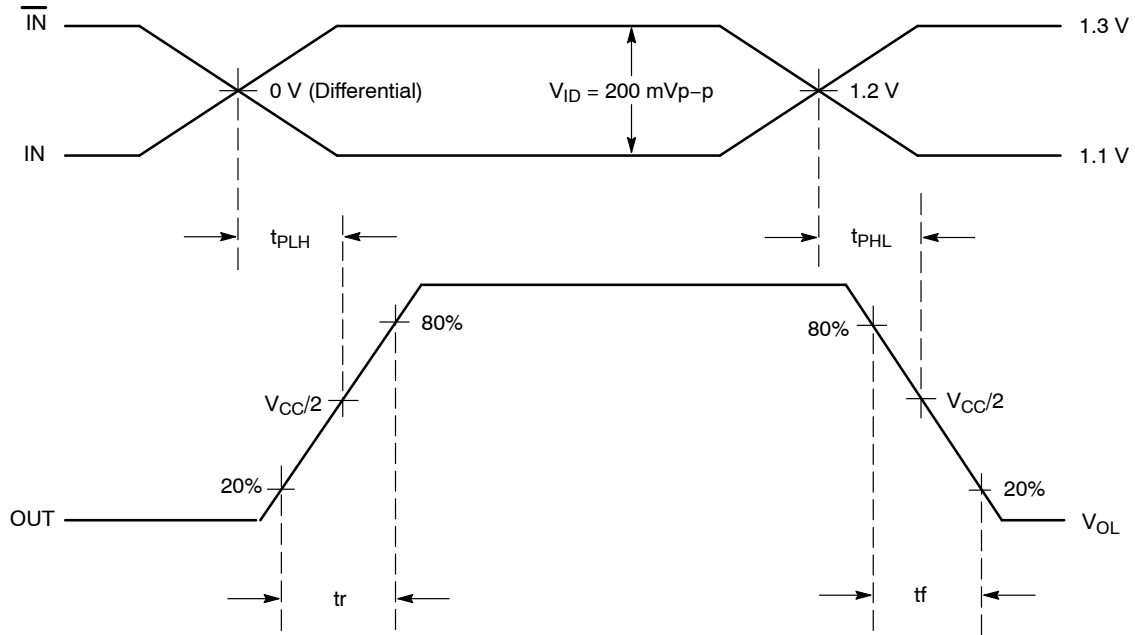
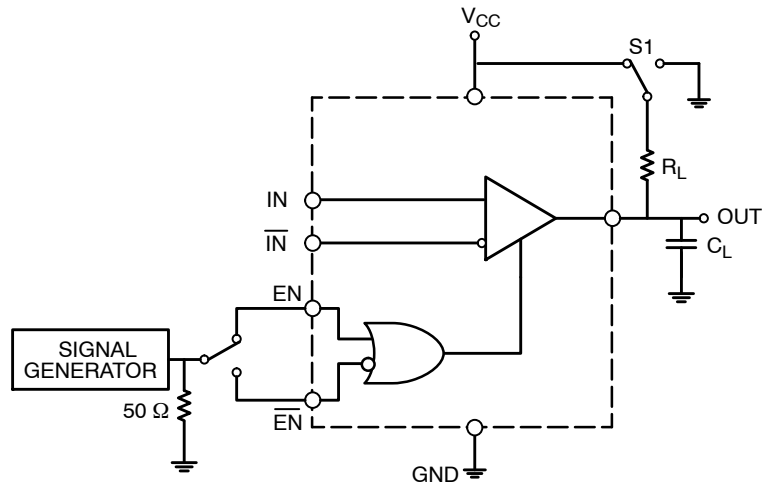


Figure 8. Receiver Propagation Delay, Rise and Fall Time

NB3N4666C



Notes:

1. C_L = Load and test jig capacitance (10 pF typical).
2. S1 connected to V_{CC} for T_{PZL} and T_{PLZ} measurements.
3. S1 connected to GND for T_{PZH} and T_{PHZ} measurements.

Figure 9. Test Circuit for Receiver Enable/Disable Delay

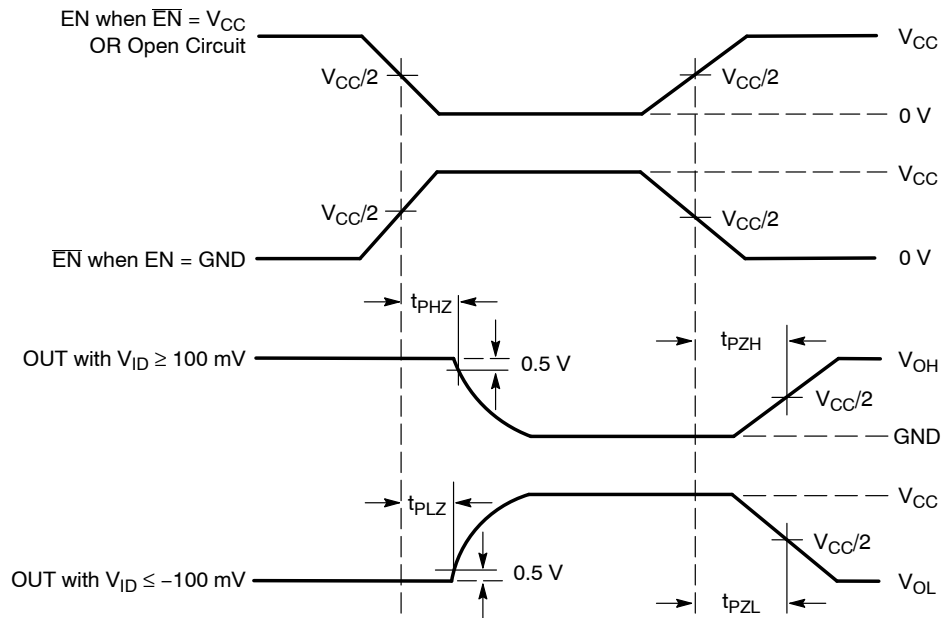
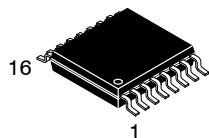


Figure 10. Receiver Enable/Disable Delay Waveform

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|------------------------------------|-----------------------|
| NB3N4666CDTR2G | TSSOP-16 5.0 x 4.4 mm (Pb-Free) | 2500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.


TSSOP-16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006

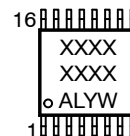

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.18 | 0.28 | 0.007 | 0.011 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

**RECOMMENDED
SOLDERING FOOTPRINT***


*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***


XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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